



Products
Single & double sided Rigid
Single & Double sided flex
Rigid Multi layer
Multi layer Flexible
Multi layer Flexi-rigid
Mixed composite multilayer
Mixed composite Flex rigid multilayer
IMS (Insulated metal substrates)
Bonded External heat sinks

Product Technology
Blind via
Micro via
Buried via
Copper filled vias
Stacked micro via
Stepped micro via
Controlled Impedance
Embedded Resistors
Embedded devices
CTE- CIC / Carbon / Aramid / Molybdenum
Resin filled through vias
Resin filled buried vias
Resin filled blind vias
Plugged vias
Thermal Management: up to 400 Microns of CU
External heat sinks: Copper / Aluminium
Heat exchangers
Metal backed substrates